ABSTRACT

Disclosed is a substrate electroplating method, comprising: configuring a substrate in an electroplating bath, the substrate having a surface to be electroplated, the electroplating bath containing an electroplating solution and being provided with a deformable diffusion plate, wherein the deformable diffusion plate has a first surface, and the first surface faces the surface to be electroplated; adjusting the shape of the deformable diffusion plate to adjust the spacing between the first surface (from the central region to the edge region) and the surface to be electroplated; electroplating metal onto the surface to be electroplated of the substrate. The present invention, by adjusting the shape of the deformable diffusion plate, can adjust the spacing between the first surface (from the central region to the edge region) and the surface to be electroplated of the substrate without reassembling the deformable diffusion plate, thereby adjusting the electric field distribution on the surface to be electroplated of the substrate, so that the surface to be electroplated of the substrate has a desired metal deposition thickness distribution.